



## EtraLED-CIT-9650 Citizen Modular Passive Star LED Heat Sink Φ96mm

### **Features VS Benefits**

- \* The EtraLED-CIT-9650 Citizen modular passive star LED heat sink are specifically designed for luminaires using the Citizen LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 2,000 to 5,100 lumen.
- \* Thermal resistance range Rth 1.45°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of citizen COB series.
- \* Diameter 96mm standard height 50mm Other heights on request.
- \* Extruded from highly conductive aluminum.

### Zhaga LED engine and radiator assembly is a unified future international standardization

- \* Below you find an overview of Citizen COB's and LED modules which standard fit on the srar LED heat sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.



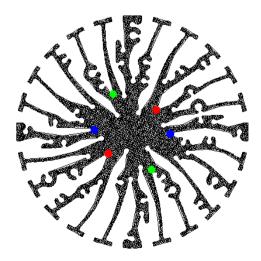














CLU046-12xxxx; CLU048-12xxxx CLU046-18xxxx; CLU048-18xxxx;

#### Citizen High intensity COB Series:

BJB holder: 47.319.2030.50; AAG.STUCCHI: 8102-G2 Direct mounting with machine screws M3x6.5mm

## Citizen LED Modules directly Mounting Options

Citizen COB version 4, version 5, version 6 Series:

CLU038-12xxxx

Citizen High intensity COB Series:

With the Zhaga Book 3 holders for the green indicator marks. Direct mounting with machine screws M3x6.5mm





# **Mounting Options and Drawings & Dimensions**

Example: EtraLED-CIT-9650-B-1,2

Example:EtraLED-CIT-96 1 - 2

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

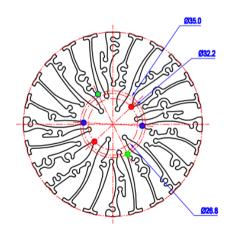
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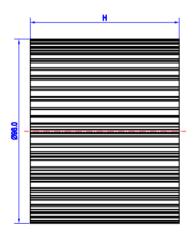
means option 1 and 2 combined

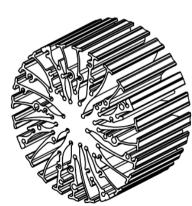
### **Notes:**

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	CLU036; CLU038 CLU721; CLU711	/	М3	6.5mm	26.8mm/ 2-@180°
2	CLU046; CLU048 CLU731	/	М3	6.5mm	32.2mm/ 2-@180°
3		BJB Holder 47.319.2030.50	МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		AAG.STUCCHI 8102-G2			
	CLU036; CLU038 CLU721; CLU711	BJB Holder 47.319.2021.50			
		AAG.STUCCHI 8101-G2			

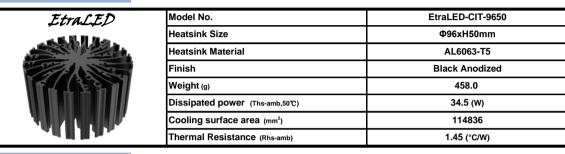








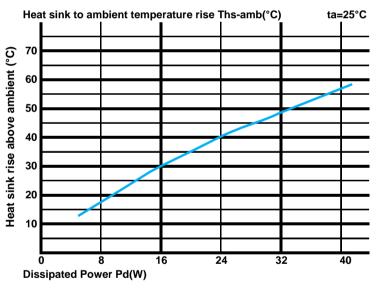
# The product deta table



### The thermal data table

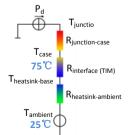
- \* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- \*To calculate the dissipated power please use the following formula:  $Pd = Pe \times (1-\eta L)$ .
  - Pd Dissipated power ; Pe Electrical power ;  $\eta L =$  Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		EtraLED-CIT-9650		
Dissipated Power Pd(W)	8.0	2.25	18.0	
	16.0	1.88	30.0	
	24.0	1.67	40.0	
	32.0	1.50	48.0	
	40.0	1.40	56.0	



- \*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

  MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.\ I-0.\ I\ 5mm\ is\ recommended.$



- \*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (Ths Ta)/Pd$
- $\theta\,$  Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- \*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{\text{junction-case}}$ , the thermal resistance of the TIM outside the package is  $R_{\text{interface}}(TIM)$  [°C/W], the thermal resistance with the heat sink is  $R_{\text{heatsink-ambient}}$  [°C/W], and the ambient temperature is  $T_{\text{ambient}}$  [°C].
- \*Thermal resistances outside the package  $R_{\text{interface (TIM)}}$  and  $R_{\text{heatsink-ambient}}$  can be integrated into the thermal resistance  $R_{\text{case-ambient}}$  at this point. Thus, the following formula is also used:  $T_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot Pd + T_{\text{ambient}}$



